



DataSpeed® Engineering Bond

Designed for high-volume, wide format xerographic applications

DataSpeed® Engineering Bond paper is designed for high volume, wide format xerographic applications.

Features/Benefits

- Superior print performance and toner adhesion
- Excellent converting performance
- Meets ANSI Type I OCR dirt guidelines
- Meets ANSI Type III OCR fluorescence guidelines
- Guaranteed performance in wide format xerographic applications
- Designed for use with leading OEM xerographic printers

Your best choice for engineering drawings, architectural plans, large format diagrams and charts.

Engineering Bond

GRADE CODE	BASIS WT* (LBS)	CALIPER (MIL)	SMOOTHNESS (SU)	BRIGHTNESS (GE)	OPACITY (%)	MOISTURE (%)
16617	20	4.0	170	92	88	4.7
16617	24	4.7	170	92	91	4.7

*Based on 17" x 22" sheet

Environmental

- Elemental Chlorine Free (ECF)
- Acid-free manufacturing process for archival properties
- Sustainable Forestry Initiative® (SFI®) certified
- Forest Stewardship Council® (FSC®) and Programme for the Endorsement of Forest Certification (PEFC) available upon request

